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TITLE: METHOD AND SYSTEM FOR SUPPORTING
MULTIPLE CACHE CONFIGURATIONS

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METHOD AND SYSTEM FOR SUPPORTING
MULTIPLE CACHE CONFIGURATIONS

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BACKGROUND OF THE INVENTION

Referring to FIG. 1, an electrical coupling network between a static random access memory 20a (hereinafter “SRAM 20a”) and a static random access memory 20b (hereinafter “SRAM 20b”) is shown. SRAM 20a and SRAM 20b are identical memory devices. Specifically, both SRAM 20a and SRAM 20b have an identical pin arrangement including seven (7) rows and seventeen (17) columns of pins. The first column of pins are shown in FIG. 1. In the first column of pins, SRAM 20a includes two (2) output power supply pins 21a and 27a, and SRAM 20b includes two (2) output power supply pins 21b and 27b. Also in the first column of pins, SRAM 20a includes four (4) synchronous address input pins 22a, 23a, 25a, and 26a, and SRAM 20b includes four (4) synchronous address input pins 22b, 23b, 25b, and 26b. Pin 24a of SRAM 20a and pin 24b of SRAM 20b are not utilized.

In support of four (4) cache configurations, SRAM 20a is mounted to a front side of a processor card 10, and SRAM 20b is mounted to a rear side of processor card 10. SRAM 20a and SRAM 20b are positioned with an alignment of pin 21a and pin 27b, an alignment of pin 22a and pin 26b, an alignment of pin 23a and pin 25b, an alignment of pin 24a and pin 24b, an alignment of pin 25a and pin 23b, an alignment of pin 26a and pin 22b, and an alignment of pin 27a and pin 21b.

Pin **22a** and pin **22b** are functionally equivalent and electrically coupled via a conductor **28a** within processor card **10** to concurrently receive a first address bit signal from a microprocessor. Pin **23a** and pin **23b** are functionally equivalent and electrically coupled via a conductor **28b** within processor card **10** to concurrently receive a second address bit signal from the microprocessor. Pin **25a** and pin **25b** are functionally equivalent and electrically coupled via a conductor **28c** within processor card **10** to concurrently receive a third address bit signal from the microprocessor. Pin **26a** and pin **26b** are functionally equivalent and electrically coupled via a conductor **28d** within processor card **10** to concurrently receive a fourth address bit signal from the microprocessor. The four (4) address bits signal are selectively provided by the microprocessor as a function of a selected cache configuration.

A drawback associated with the aforementioned electrical couplings as shown is the length of conductors **28a–28d** tends to establish a maximum frequency at which the microprocessor can effectively and efficiently control SRAM **20a** and SRAM **20b**, and the established maximum frequency can be significantly lower than a desired operating frequency of the microprocessor. The computer industry is therefore continually striving to improve upon the electrical coupling between the synchronous address input pins of SRAM **20a** and SRAM **20b** whereby a maximum frequency at which a microprocessor can effectively and efficiently control SRAM **20a** and SRAM **20b** matches a desired operating frequency of the microprocessor. The computer industry is also continually striving to improve upon the electrical communication of a selected cache configuration from a microprocessor to the synchronous address input pins of SRAM **20a** and SRAM **20b**.

Field Of The Invention

The present invention generally relates to computer hardware mounted upon a processor card, and in particular to an electrical coupling between 5 memory components for supporting multiple cache configurations and an electrical communication from a microprocessor to the memory components for selecting one of the supported multiple cache configurations.

SUMMARY OF THE INVENTION

10 One form of the present invention is a processor card having a first memory device and a second memory device mounted thereon. The first memory device includes a first address pin and a second address pin. The second memory device includes a third address pin and a fourth address pin. The first address pin of the first memory device and the third address pin of the 15 second memory device are functionally equivalent address pins. The second address pin of the first memory device and the fourth address pin are functionally equivalent address pins. The first address pin of the first memory device and the fourth address pin of the second memory device are electrically coupled to thereby concurrently receive a first address bit signal. The second address pin of 20 the first memory device and the third address pin of the second memory device are electrically coupled to thereby concurrently receive a second address bit signal.

Another form of the present invention is a system including a first memory device, a second memory device, and a microprocessor. The first memory 25 device includes a first address pin and a second address pin. The second memory device includes a third address pin and a fourth address pin. The first address pin of the first memory device and the third address pin of the second memory device are functionally equivalent address pins. The second address pin of the first memory device and the fourth address pin are functionally

equivalent address pins. The microprocessor is operable to concurrently provide a first address bit signal to first address pin of the first memory device and the fourth address pin of the second memory device. The microprocessor is further

5 operable to concurrently provide a first address bit signal to second address pin of the first memory device and the third address pin of the second memory device.

The foregoing and other features and advantages of the invention will become further apparent from the following detailed description of the presently 10 preferred embodiments, read in conjunction with the accompanying drawings. The detailed description and drawings are merely illustrative of the invention rather than limiting, the scope of the invention being defined by the appended claims and equivalents thereof.

15 **BRIEF DESCRIPTION OF THE DRAWINGS**

FIG. 1 is a fragmented side view of a processor card having a pair of static random accesses memories mounted thereon with an electrical coupling of synchronous address pins as known in the art;

20 **FIG. 2** is view of the **FIG. 1** processor card and **FIG. 1** static random accesses memories with an electrical coupling of synchronous address pins in accordance with the present invention;

FIG. 3A is a general block diagram of a first embodiment of a microprocessor in accordance with the present invention;

25 **FIG. 3B** is a general block diagram of a second embodiment of a microprocessor in accordance with the present invention; and

FIG. 3C is a general block diagram of one embodiment of a microprocessor in accordance with the present invention.

**DETAILED DESCRIPTION OF THE
PRESENTLY PREFERRED EMBODIMENTS**

Referring to FIG. 2, SRAM 20a and SRAM 20b are mounted upon processor card 10 as previously described in connection with FIG. 1. In accordance with the present invention, pin 22a and pin 26b are electrically coupled via a conductor 29a within processor card 10 to concurrently receive a first address bit signal. Pin 23a and pin 25b are electrically coupled via a conductor 29b within processor card 10 to concurrently receive a second address bit signal. Pin 25a and pin 23b are electrically coupled via a conductor 29c within processor card 10 to concurrently receive a third address bit signal. Pin 26a and pin 22b are electrically coupled via a conductor 29d within processor card 10 to concurrently receive a fourth address bit signal. The length of the conductors 29a-29d facilitate an effective and efficient operation of SRAM 20a and SRAM 20b over a wide range of operating frequencies of a microprocessor.

Referring to FIG. 3A, a microprocessor 30 in accordance with the present invention for selecting between two (2) of the four (4) cache configurations supported by SRAM 20a and SRAM 20b is shown. Microprocessor 30 includes main logic units 31 for interpreting and executing operating and application programs as would occur to one skilled in the art. Microprocessor 30 further includes a controller 32 and a multiplexer 33. Address bus 32a and address bus 32b provide electrical communication between controller 32 and multiplexer 33. Address bus 32a and address bus 32b each have two (2) address lines. Multiplexer 33 has an address bus 33a with a first address line electrically coupled to pin 22a (FIG. 2) and pin 26b (FIG. 2), and a second address line electrically coupled to pin 26a (FIG. 2) and pin 22b (FIG. 2). The following Table 1 exemplary illustrates an address bit logic utilized by main logic units 31 for electrically communicating a selected cache configuration between an 8 Mbyte cache and a 16 Mbyte cache to SRAM 20a and SRAM 20b.

TABLE 1

ADDRESS BUS	CACHE SIZE	FIRST ADDRESS LINE (MSB)	SECOND ADDRESS LINE (LSB)
32a	8 Mbyte	net2	net2
32b	16 Mbyte	net1	net2

Still referring to FIG. 3A, microprocessor 30 further comprises a

- 5 configuration register 34. Configuration register 34 provides a control signal to multiplexor 33 via a control bus 34a in response to a selection signal from main logic units 31 via a data bus 31a. The selection signal is indicative of a selected cache configuration by main logic units 31 during an initial boot of microprocessor 30. The control signal is indicative of the address bus that
- 10 corresponds to the selected cache configuration. Consequently, multiplexor 33 provides the appropriate address signals via address bus 33a to SRAM 20a and SRAM 20b in response to the selection signal. For example, when the selection signal indicates the 16 Mbyte cache has been selected during an initial boot of microprocessor 30, pin 22a and pin 26b concurrently receive address signal
- 15 net1, and pin 26a and pin 22b concurrently receive address signal net2 as indicated by Table 1.

Referring to FIG. 3B, a microprocessor 40 in accordance with the present invention for selecting between three (3) of the four (4) cache configurations supported by SRAM 20a and SRAM 20b is shown. Microprocessor 40 includes

- 20 main logic units 41 for interpreting and executing operating and application programs as would occur to one skilled in the art. Microprocessor 40 further includes a controller 42 and a multiplexer 43. Address bus 42a, address bus 42b, and address bus 42c provide electrical communication between controller

42 and multiplexer 43. Address bus 42a address bus 42b, and address bus 42c each have three (3) address lines. Multiplexer 43 has an address bus 43a with a first address line electrically coupled to pin 22a (FIG. 2) and pin 26b (FIG. 2), a 5 second address line electrically coupled to pin 26a (FIG. 2) and pin 22b (FIG. 2), and a third address line electrically coupled to pin 23a (FIG. 2) and pin 25b (FIG. 2). The following Table 2 exemplary illustrates the address bit logic utilized by main logic units 41 for electrically communicating a selected cache configuration between a 4 Mbyte cache, an 8 Mbyte cache and a 16 Mbyte cache 10 to SRAM 20a and SRAM 20b.

TABLE 2

ADDRESS BUS	CACHE SIZE	FIRST ADDRESS LINE (MSB)	SECOND ADDRESS LINE	THIRD ADDRESS LINE (LSB)
32a	4 Mbyte	net3	net3	net3
32b	8 Mbyte	net2	net2	net3
32c	16 Mbyte	net1	net2	net3

Still referring to FIG. 3B, microprocessor 40 further comprises a configuration register 44. Configuration register 44 provides a control signal to 15 multiplexor 43 via a control bus 44a in response to a selection signal from main logic units 41 via a data bus 41a. The selection signal is indicative of a selected cache configuration by main logic units 41 during an initial boot of microprocessor 40. The control signal is indicative of the address bus that corresponds to the selected cache configuration. Consequently, multiplexor 43 20 provides the appropriate address signals via address bus 43a to SRAM 20a and SRAM 20b in response to the selection signal. For example, when the selection

signal indicates the 8 Mbyte cache has been selected, pin **22a** and pin **26b** concurrently receive address signal net2, pin **26a** and pin **22b** concurrently receive address signal net2, and pin **23a** and pin **25b** concurrently receive address signal net3 as indicated by Table 2.

Referring to **FIG. 3C**, a microprocessor **50** in accordance with the present invention for selecting between all four (4) cache configurations supported by SRAM **20a** and SRAM **20b** is shown. Microprocessor **50** includes main logic units **51** for interpreting and executing operating and application programs as would occur to one skilled in the art. Microprocessor **50** further includes a controller **52** and a multiplexer **53**. Address bus **52a**, address bus **52b**, address bus **52c**, and address bus **52d** provide electrical communication between controller **52** and multiplexer **53**. Address bus **52a** address bus **52b**, address bus **52c**, and address bus **52d** each have four (4) address lines. Multiplexer **53** has an address bus **53a** with a first address line electrically coupled to pin **22a** (**FIG. 2**) and pin **26b** (**FIG. 2**), a second address line electrically coupled to pin **26a** (**FIG. 2**) and pin **22b** (**FIG. 2**), a third address line electrically coupled to pin **23a** (**FIG. 2**) and pin **25b** (**FIG. 2**), and a fourth address line electrically coupled to pin **23b** (**FIG. 2**) and pin **25a** (**FIG. 2**). The following Table 3 exemplary illustrates the address bit logic utilized by main logic units **51** for electrically communicating a selected cache configuration between a 2 Mbyte cache, a 4 Mbyte cache, an 8 Mbyte cache and a 16 Mbyte cache to SRAM **20a** and SRAM **20b**.

TABLE 3

ADDRESS BUS	CACHE SIZE	FIRST ADDRESS LINE (MSB)	SECOND ADDRESS LINE	THIRD ADDRESS LINE	FOURTH ADDRESS LINE (LSB)
32a	2 Mbyte	net4	net4	net4	net4
32b	4 Mbyte	net3	net3	net3	net4
32c	8 Mbyte	net2	net2	net3	net4
32d	16 Mbyte	net1	net2	net3	net4

Still referring to FIG. 3C, microprocessor 50 further comprises a

- 5 configuration register 54. Configuration register 54 provides a control signal to multiplexor 53 via a control bus 54a in response to a selection signal from main logic units 51 via a data bus 51a. The selection signal is indicative of a selected cache configuration by main logic units 51 during an initial boot of microprocessor 50. The control signal is indicative of the address bus that
- 10 corresponds to the selected cache configuration. Consequently, multiplexor 53 provides the appropriate address signals via address bus 53a to SRAM 20a and SRAM 20b in response to the selection signal. For example, when the selection signal indicates the 8 Mbyte cache has been selected, pin 22a and pin 26b concurrently receive address signal net2, pin 26a and pin 22b concurrently
- 15 receive address signal net2, pin 23a and pin 25b concurrently receive address signal net3, and pin 23b and pin 25a concurrently receive address signal net4 as indicated by Table 3.

From the previous description of SRAM **20a** and SRAM **20b** herein in connection with **FIG. 2**, one skilled in the art will know how to make and use electrical couplings between additional synchronous address pins of SRAM **20a** and SRAM **20b** in accordance with the present invention. From the previous description of microprocessors **30**, **40**, and **50** in connection with **FIGS. 3A-3C**, respectively, one skilled in the art will know how to make and use microprocessors in accordance with the present invention for selecting a cache configuration between five or more supported cache configurations.

10 While the embodiments of the present invention disclosed herein are presently considered to be preferred, various changes and modifications can be made without departing from the spirit and scope of the invention. The scope of the invention is indicated in the appended claims, and all changes that come within the meaning and range of equivalents are intended to be embraced

15 therein. For examples, the pin configuration and size of SRAM **20a** and SRAM **20b** can vary, and/or SRAM **20a** and SRAM **20b** may include asynchronous address pins. Additionally, SRAM **20a** and SRAM **20b** may be misaligned along the respective sides of processor card **10**, and/or mounted on the same side of processor card **10**. Also, other memory devices may be utilized in lieu of SRAM

20 **20a** and SRAM **20b**, e.g. dynamic static random access memories.